



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STNS01PUR	MRPI*U1A3AA5	A	SA1A	2016-11-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	20.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	3.0,3.0,0.75	12	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2013/28/EU _ May 2013	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description
	#N/A

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MRPI*U1A3AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	2.032	mg	supplier	die	Silicon (Si)	7440-21-3		1.860	mg	916057	93850
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	13177	1350
				supplier	metallization	Tungsten (W)	7440-33-7		0.021	mg	10249	1050
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	2928	300
				supplier	Passivation	Silicon Oxide	7631-86-9		0.045	mg	21962	2250
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.045	mg	21962	2250
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.028	mg	13665	1400
				supplier	Alloy	Copper(Cu)	7440-50-8		8.120	mg	965900	409542
Leadframe	Copper & its alloys	8.407	mg	supplier	Alloy	Iron(Fe)	7439-89-6		0.190	mg	22560	9565
				supplier	Alloy	Lead(Pb)	7439-92-1		0.000	mg	30	13
				supplier	Alloy	Phosphorus	7723-14-0		0.002	mg	240	102
				supplier	Alloy	Zinc	7440-66-6		0.011	mg	1270	538
				supplier	Alloy	Silver(Ag)	7440-22-4		0.084	mg	10000	4240
				supplier	Adhesive	Silver (Ag)	7440-22-4		0.062	mg	850000	3103
Die attach	Other Organic Materials	0.072	mg	supplier	Adhesive	Carbocyclic acrylate	proprietary		0.007	mg	100000	365
				supplier	Adhesive	2-Propenoic acid, 2-methyl-, 2-[[2,3,3a,4,7,7a	68586-19-6		0.003	mg	45000	164
				supplier	Adhesive	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.000	mg	5000	18
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.124	mg	1000000	6250
Bonding wire	Other inorganic materials	0.124	mg	supplier	Bonding wire	Silica Fused (Si)	60676-86-0		8.405	mg	937000	423993
				supplier	Mold compound	Epoxy Resin	Proprietary		0.269	mg	30000	13575
				supplier	Mold compound	Phenol Resin	Proprietary		0.269	mg	30000	13575
				supplier	Mold compound	Carbon Black (C)	1333-86-4		0.027	mg	3000	1358
Encapsulation	Other Organic Materials	8.970	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		0.394	mg	1000000	19900
				supplier	Connection coating	Tin(Sn)	7440-31-5		0.394	mg	1000000	19900